

MECHANICAL CASE OUTLINE

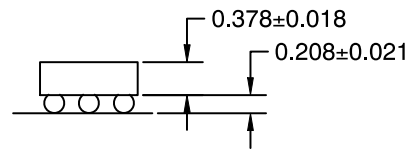
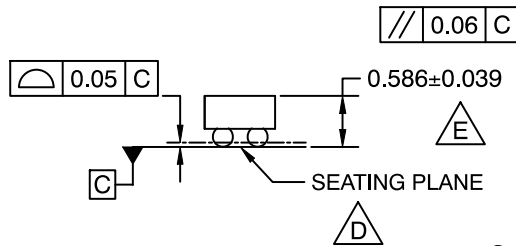
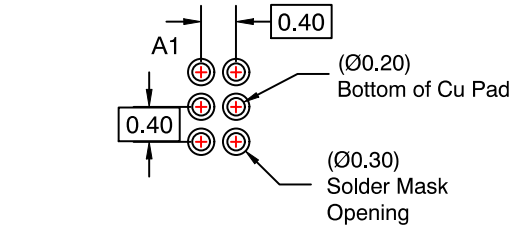
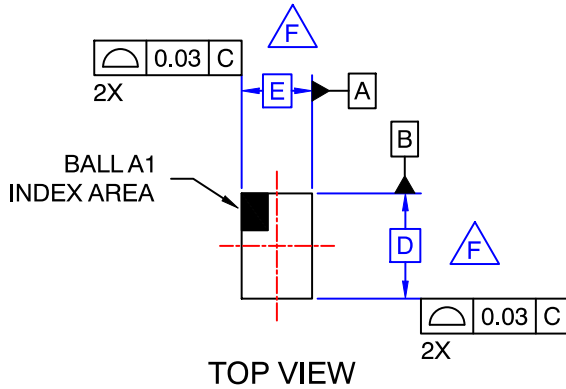
PACKAGE DIMENSIONS

ON Semiconductor®



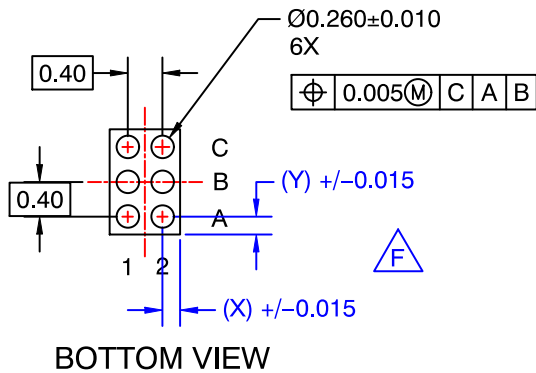
WLCSP6 1.31x0.96x0.586
CASE 567RS
ISSUE O

DATE 30 NOV 2016



NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASMEY14.5M, 2009.
- D.** DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E.** PACKAGE TYPICAL HEIGHT IS 586 MICRONS ±39 MICRONS (547–625 MICRONS).
- F.** FOR DIMENSIONS D, E, X, AND Y, SEE PRODUCT DATASHEET.



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